

Base materials for printed circuits —

Part 2: Specifications —

Specification No. 13 Flexible copper-clad polyimide film, general purpose grade

The European Standard EN 60249-2-13:1994 + A1:1994 has the status of a British Standard

Committees responsible for this British Standard

The preparation of this British Standard was entrusted by the Electronic Components Standards Policy Committee (ECL/-) to Technical Committee ECL/19, upon which the following bodies were represented:

- British Telecommunications plc
- EEA (The Electronics and Business Equipment Association)
- Electrical and Electronic Insulation Association (BEAMA Ltd.)
- Electronic Components Industry Federation
- GAMBICA (BEAMA Ltd.)
- Institute of Metal Finishing
- Ministry of Defence
- National Supervising Inspectorate
- Printed Circuit Association
- Printed Circuit Interconnection Federation
- Surface Mounted and Related Technologies Ltd.
- Telecommunication Engineering and Manufacturing Association

This British Standard, having been prepared under the direction of the Electronic Component Standards Policy Committee, was published under the authority of the Board of BSI and comes into effect on 28 February 1990

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The following BSI references relate to the work on this standard:
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National foreword

This Section of BS 4584 has been prepared under the direction of the Electronic Components Standards Policy Committee. It is identical with both CENELEC harmonized document HD 313-2-13 S1 and IEC 249-2-13:1987 “*Base materials for printed circuits*” Part 2: “*Specifications*”, Specification No. 13 “*Flexible copper-clad polyimide film, general purpose grade*”, published by the International Electrotechnical Commission (IEC).

In 1994 the European Committee for Electrotechnical Standardization (CENELEC) accepted IEC 249-2-13:1987 and its amendment 1:1993 as European Standard EN 60249-2-13:1994 and its amendment A1:1994. As a consequence of implementing the European Standard and its amendment this British Standard is numbered as BS EN 60249-2-13:1994 and any reference to BS 4584-102.5:1990 should be read as a reference to BS EN 60249-2-13:1994.

This Section is one of a series of specifications for base material for printed circuits. This series of specifications replaces the previously published Parts of BS 4584 which are listed below. The following list provides a guide to the relation between these withdrawn Parts and the new specifications. Note that inclusion in the list does not necessarily indicate an exact correspondence between the Parts but only a technical relationship.

Withdrawn Part	Replacement Section
2 (1972)	102.4 (1990)
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5 (1972)	None
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9 (1977)	102.8 (1990)
10 (1977)	102.15 ^a
11 (1977)	103.1 (1990)
12 (1977)	102.12 (1990)
13 (1977)	None
14 (1989)	102.6 (1990)
16 (1978)	102.10 (1990)

^a In preparation.

Cross-references

International Standard	Corresponding British Standard
	BS 4584 <i>Metal-clad base materials for printed wiring boards</i>
IEC 249-1:1982	Part 1:1983 <i>Methods of test</i> (Identical)
IEC 249-3A:1976	Part 103: <i>Special materials used in connection with printed circuits.</i> Section 103.2:1990 <i>Specification for copper foil for use in the manufacture of copper-clad base materials</i> (Identical)

A British Standard does not purport to include all the necessary provisions of a contract. Users of British Standards are responsible for their correct application.

Compliance with a British Standard does not of itself confer immunity from legal obligations.

Summary of pages

This document comprises a front cover, an inside front cover, pages i to iv, the EN title page, pages 2 to 10, an inside back cover and a back cover.

This standard has been updated (see copyright date) and may have had amendments incorporated. This will be indicated in the amendment table on the inside front cover.

